

SOT-23-6L Plastic-Encapsulate MOSFETS

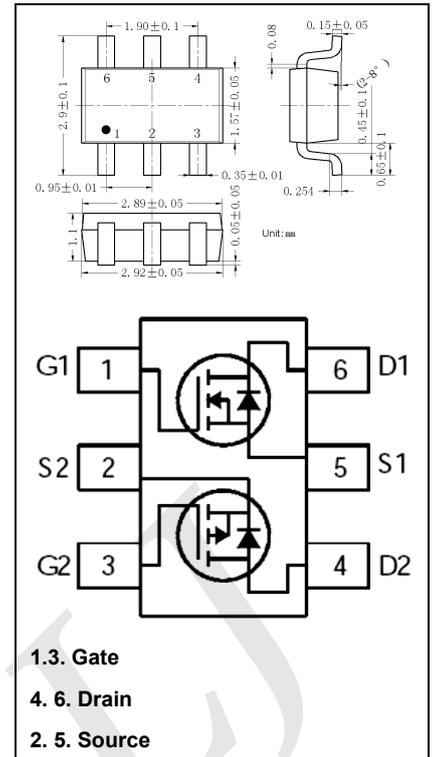
APM2701

20V Complementary Enhancement Mode Field Effect Transistor

Features

- | | |
|-----------------------------|---------------------------------|
| N-channel | P-channel |
| ■ $V_{DS} (V) = 20V$ | $V_{DS} (V) = -20V$ |
| ■ $I_D = 4A$ | $I_D = -2.5A$ |
| ■ $R_{DS(ON)}$ | $R_{DS(ON)}$ |
| < $35m\Omega (V_{GS}=4.5V)$ | < $85m\Omega (V_{GS} = -4.5V)$ |
| < $42m\Omega (V_{GS}=2.5V)$ | < $115m\Omega (V_{GS} = -2.5V)$ |

Marking: 52907



Description

The APM2701 combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. This device is ideal for load switch and battery protection applications.

Maximum Ratings ($T_A=25^\circ C$ unless otherwise specified)

Symbol	Parameter	N-Channel	P-Channel	Unit	
V_{DSS}	Drain-Source voltage	20	-20	V	
V_{GSS}	Gate-Source voltage	± 12	± 12		
I_D	Continuous Drain Current ^{1, 3)}	$T_A = 25^\circ C$	4	-2.5	A
		$T_A = 70^\circ C$	3.2	-2	
I_{DM}	Pulsed Drain Current ²⁾	13	-13	A	
P_D	Power Dissipation	$T_A = 25^\circ C$	1.1		W
		$T_A = 70^\circ C$	0.7		
T_J, T_{stg}	Operating Temperature/ Storage Temperature	-55 ~ +150		$^\circ C$	

Electrical Characteristics (T_J=25°C unless otherwise specified)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit		
Static								
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA	N-Ch	20		V		
		V _{GS} = 0V, I _D = -250μA	P-Ch	-20				
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 20V, V _{GS} = 0V	N-Ch		1	μA		
		V _{DS} = -20V, V _{GS} = 0V	P-Ch		-1			
V _{GS(th)}	Gate-Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	N-Ch	0.6	0.75	1.0	V	
		V _{DS} = V _{GS} , I _D = -250μA	P-Ch	-0.5	-0.6	-1.0		
I _{GSS}	Gate-body Leakage current	V _{DS} = 0V, V _{GS} = ±12V			±100	nA		
R _{DS(on)}	Drain-Source On-Resistance	V _{GS} = 4.5V, I _D = 3.5A	N-Ch		29	35	mΩ	
		V _{GS} = -4.5V, I _D = -2.8A	P-Ch		77	85		
		V _{GS} = 2.5V, I _D = 2.5A	N-Ch		35	42		
		V _{GS} = -2.5V, I _D = -2.0A	P-Ch		92	115		
		V _{GS} = 1.8V, I _D = 2A	N-Ch		62	75		
		V _{GS} = -2.5V, I _D = -2.0A	P-Ch		118	200		
g _{FS}	Forward Transconductance	V _{DS} = 5V, I _D = 3A	N-Ch		16	S		
		V _{DS} = -5V, I _D = 2.5A	P-Ch		13			
V _{SD}	Diode Forward Voltage	V _{GS} = 0V, I _S = 1.7A	N-Ch		0.74	1.0	V	
		V _{GS} = 0V, I _S = -1.6A	P-Ch		-0.81	-1.0		
I _S	Maximum Body-Diode Continuous Current		N-Ch			1.7	A	
			P-Ch			-1.6		
Dynamic								
C _{iss}	Input Capacitance	N-mos: V _{DS} = 8V, V _{GS} = 0V, f = 1MHz P-mos: V _{DS} = -6V, V _{GS} = 0V, f = 1MHz	N-Ch		522.3	pF		
			P-Ch		589			
C _{oss}	Output Capacitance		N-Ch		98.5			
			P-Ch		91.2			
C _{rss}	Reverse Transfer Capacitance		N-Ch		74.7			
			P-Ch		67.2			
Switching								
Q _g	Total Gate Charge	N-mos: V _{DD} = 10V, V _{GS} = 4.5V, I _D = 4A P-mos: V _{DD} = -6V, V _{GS} = -4.5V I _D = -2.8A	N-Ch		6.3	8.1	nC	
			P-Ch		6.6	8.6		
Q _{gs}	Gate-Source Charge		N-Ch		1.7	2.2		
			P-Ch		0.3	0.4		
Q _{gd}	Gate-Drain Charge		N-Ch		1.4	1.8		
			P-Ch		1.3	1.7		
t _{d(on)}	Turn-On Delay Time		N-Ch		10.4	20.8		ns
			P-Ch		9.7	19.4		
t _r	Rise Time	N-Ch		4.4	8.8			
		P-Ch		3.6	7.1			
t _{d(off)}	Turn-Off Delay Time	N-Ch		27.4	54.8			
		P-Ch		33.3	66.6			
t _f	Fall Time	N-Ch		4.2	8.4			
		P-Ch		4.5	9			

1: The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with TA=25°C. The value in any given application depends on the user's specific board design.

2: Repetitive rating, pulse width limited by junction temperature.

3: The current rating is based on the t_s ≤ 10s junction to ambient thermal resistance rating.

N-Channel Typical Characteristics

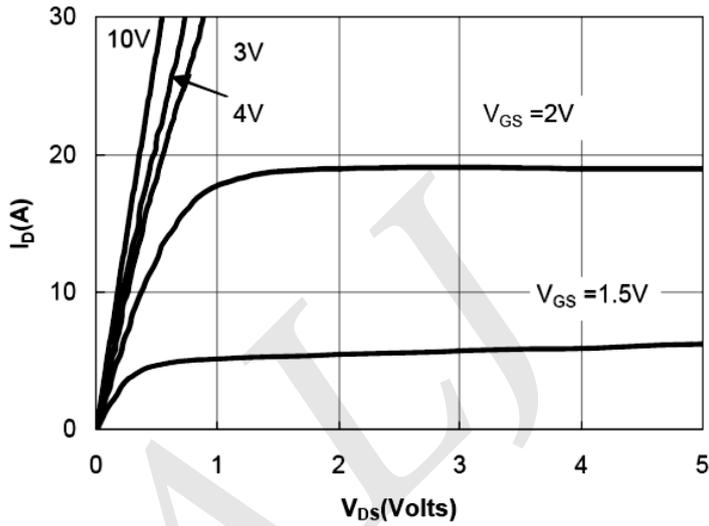


Figure 1: On-Regions Characteristic CS

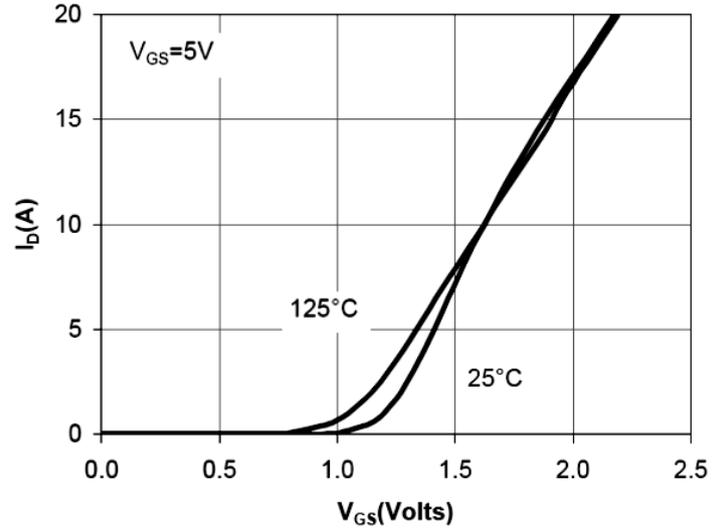


Figure 2: Transfer Characteristics

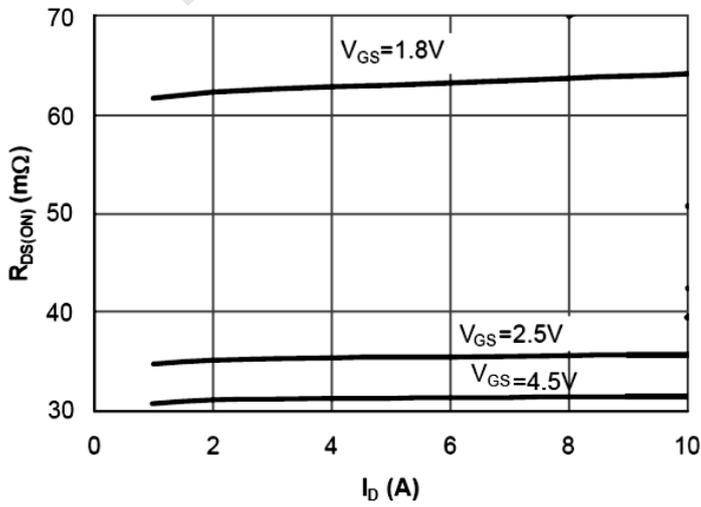


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

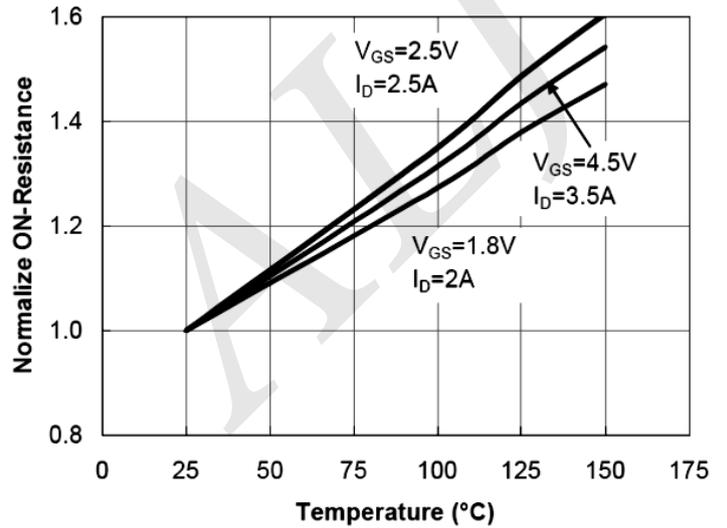


Figure 4: On-Resistance vs. Junction Temperature

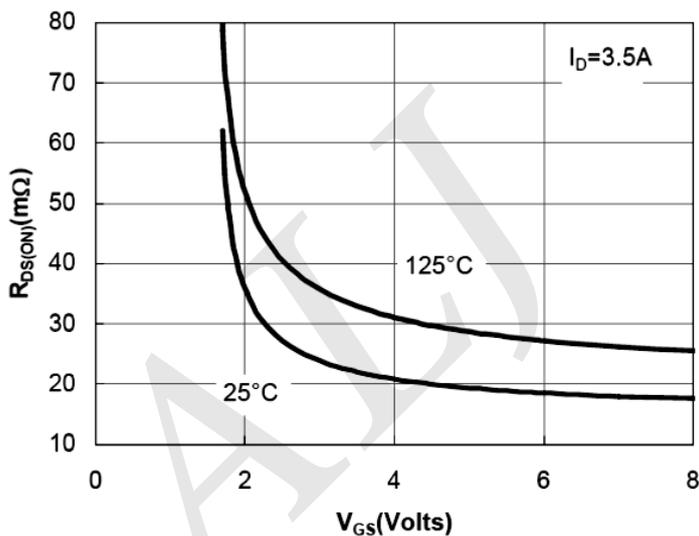


Figure 5: On-Resistance vs. Gate-Source Voltage

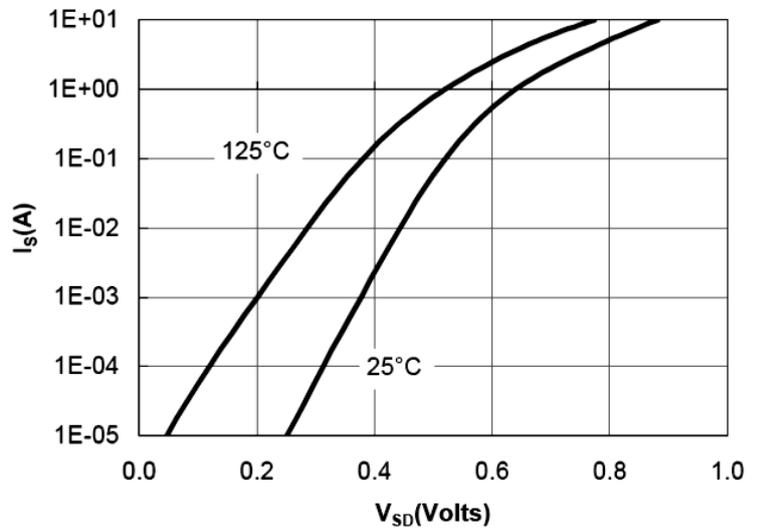


Figure 6: Body-Diode Characteristics

N-Channel Typical Characteristics (Cont.)

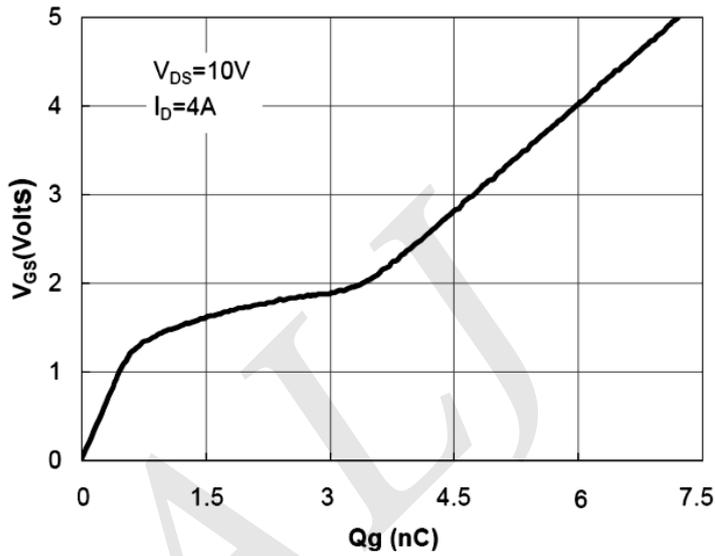


Figure 7: Gate-Charge Characteristics

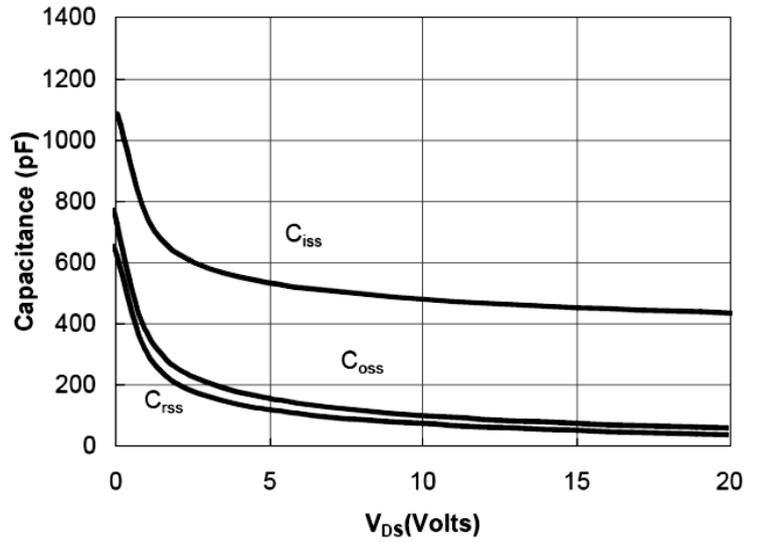


Figure 8: Capacitance Characteristics

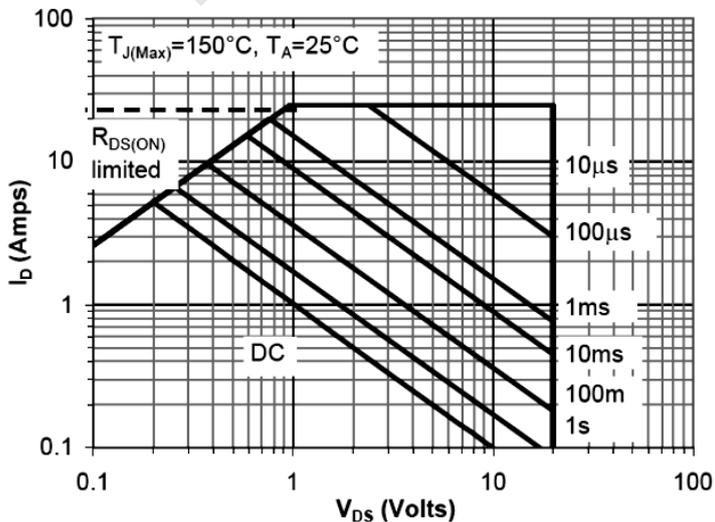


Figure 9: Maximum Forward Biased Safe Operating Area

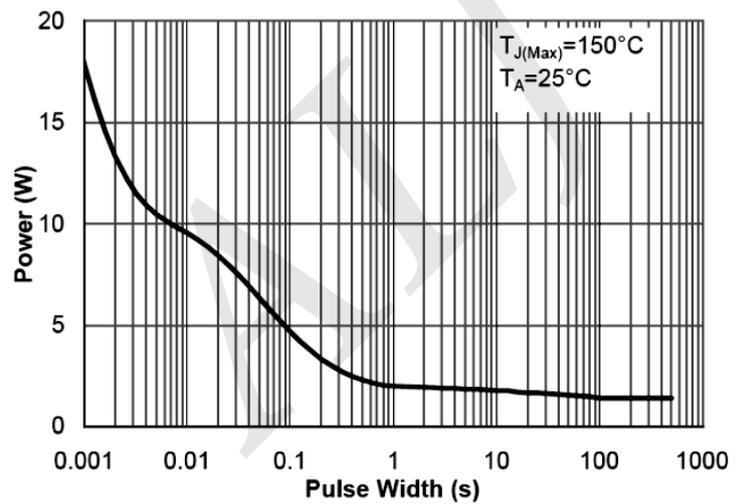


Figure 10: Single Pulse Power Rating Junction-to-Ambient

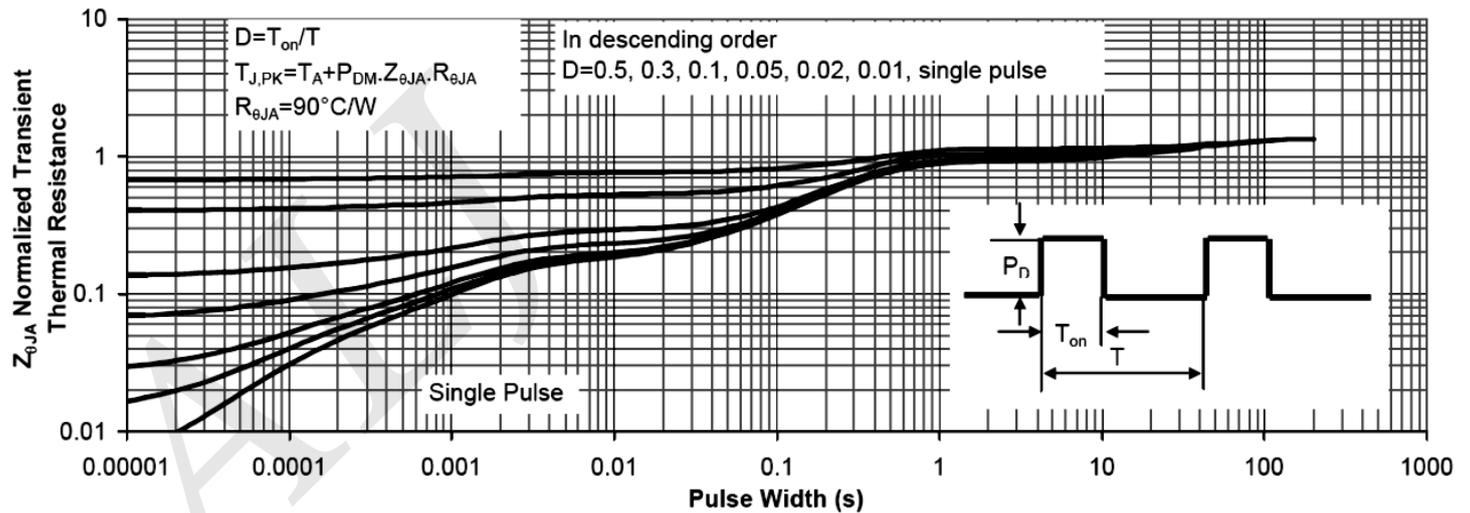


Figure 11: Normalized Maximum Transient Thermal Impedance

P-Channel Typical Characteristics

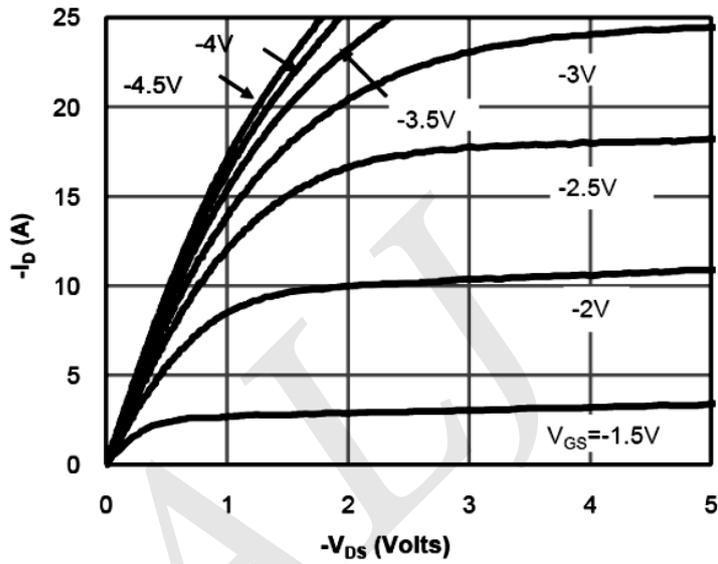


Figure 1: On-Region Characteristics

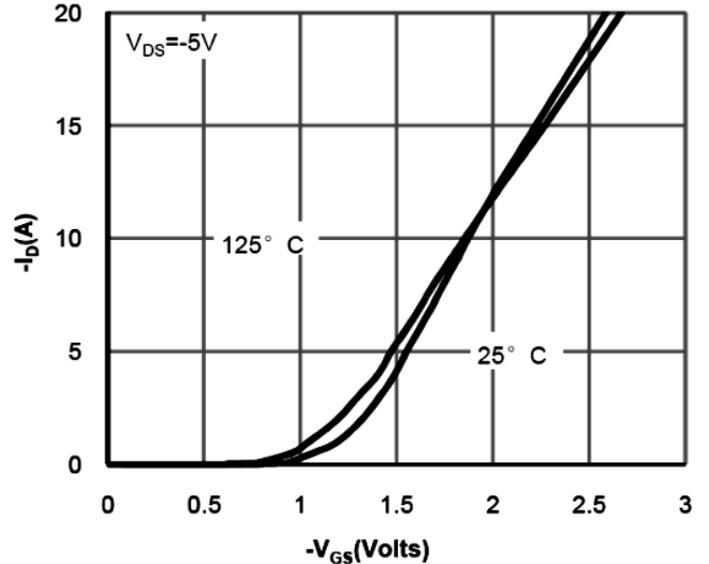


Figure 2: Transfer Characteristics

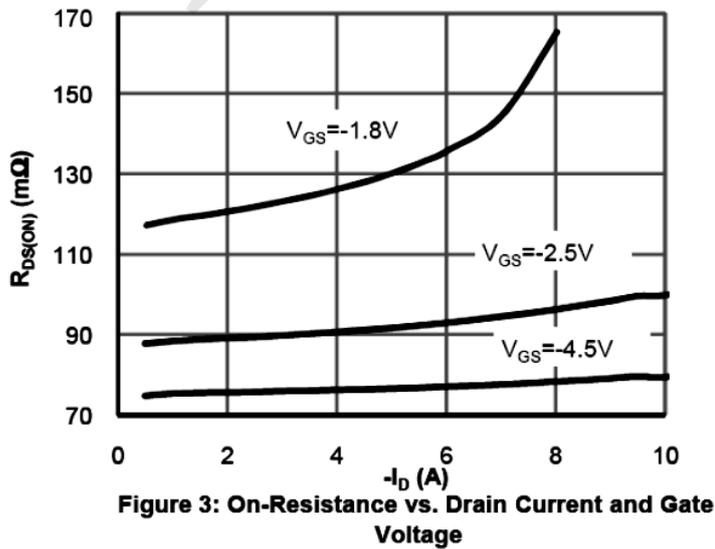


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

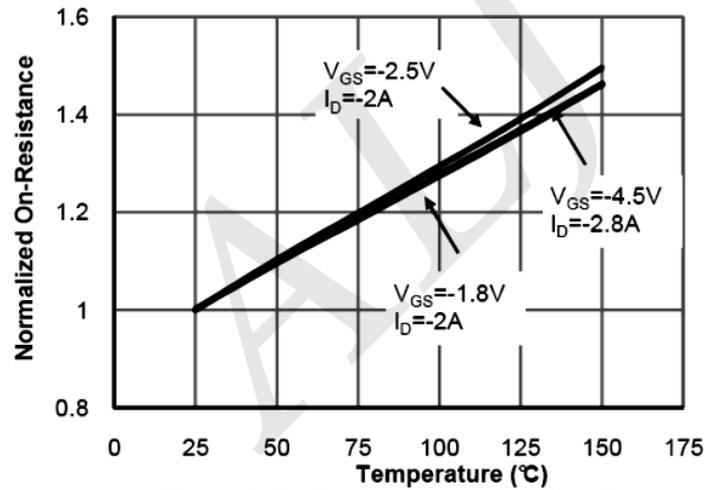


Figure 4: On-Resistance vs. Junction Temperature

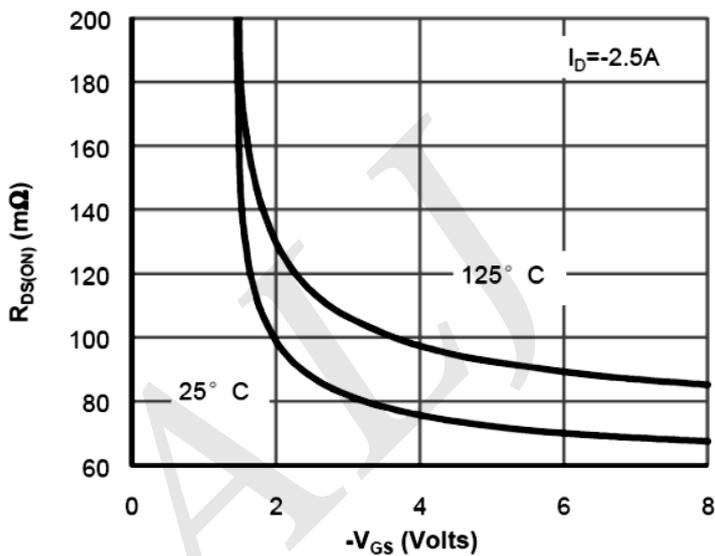


Figure 5: On-Resistance vs. Gate-Source Voltage

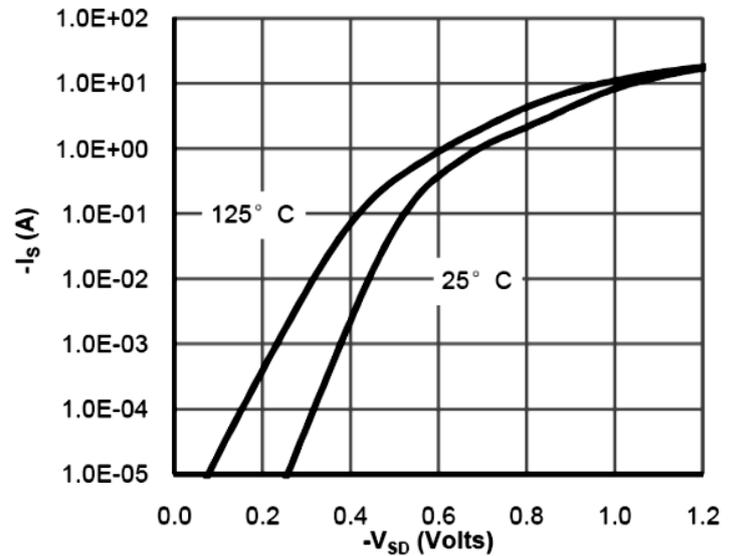


Figure 6: Body-Diode Characteristics

P-Channel Typical Characteristics (Cont.)

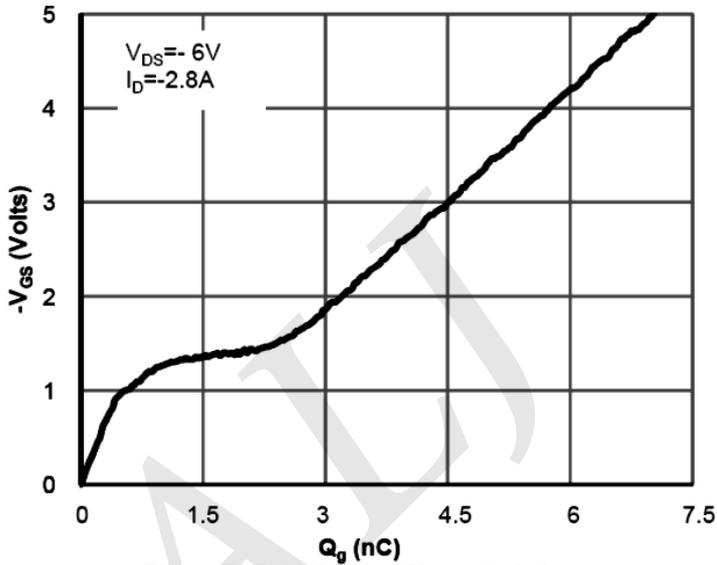


Figure 7: Gate-Charge Characteristics

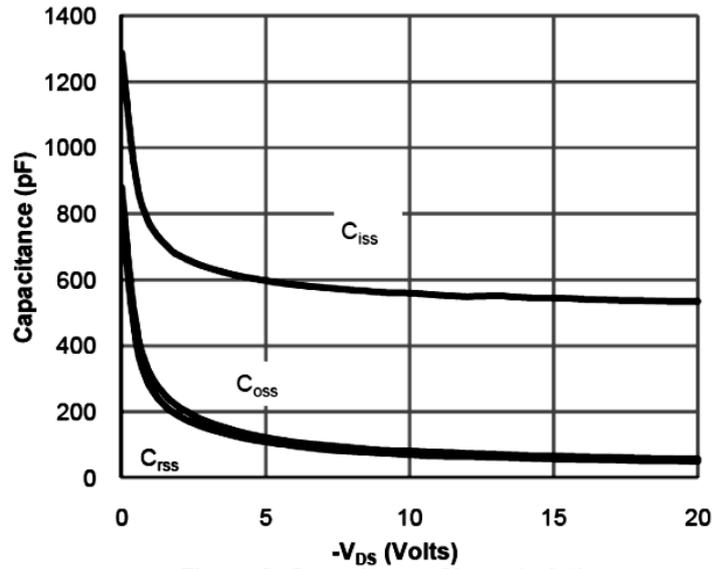


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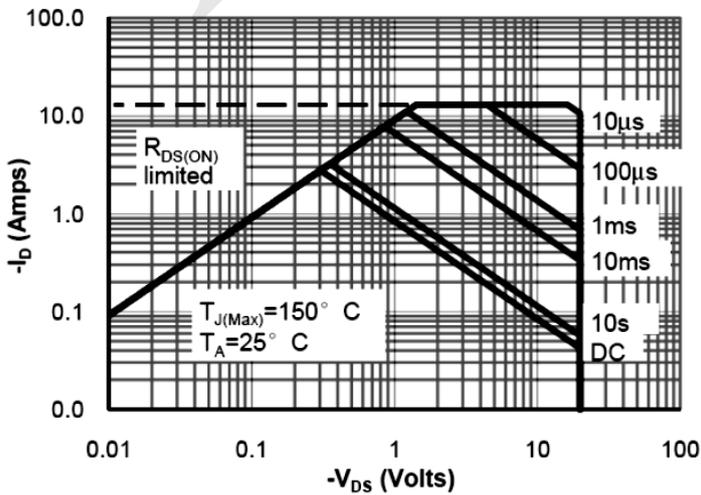


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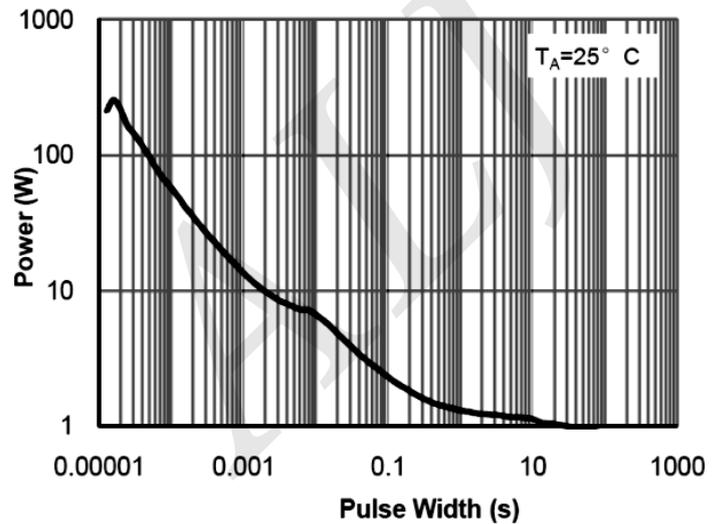


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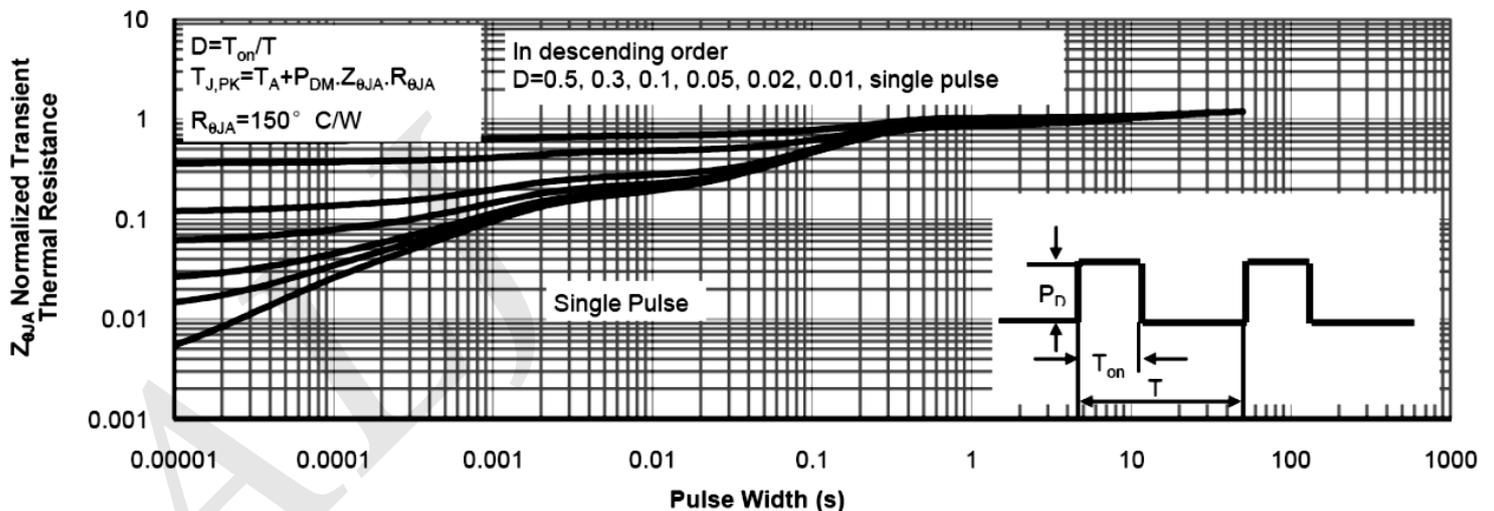


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